# 2SD2137A

### Silicon NPN triple diffusion planar type

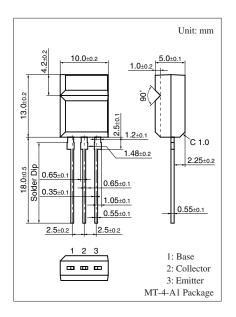
For power amplification
Complementary to 2SB1417A

#### ■ Features

- ullet High forward current transfer ratio  $h_{FE}$  which has satisfactory linearity.
- ullet Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Allowing supply with the radial taping

#### ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (En	V <sub>CBO</sub>	80	V	
Collector-emitter voltage	V <sub>CEO</sub>	80	V	
Emitter-base voltage (Collector open)		$V_{EBO}$	6	V
Collector current	$I_{C}$	3	A	
Peak collector current	$I_{CP}$	5	A	
Collector power		$P_{C}$	15	W
dissipation	$T_a = 25^{\circ}C$		2.0	
Junction temperature		T <sub>j</sub>	150	°C
Storage temperature	$T_{stg}$	-55 to +150	°C	
Peak collector current  Collector power dissipation  Junction temperature	T <sub>a</sub> = 25°C	I <sub>CP</sub> P <sub>C</sub>	5 15 2.0 150	A W °C



### $\blacksquare$ Electrical Characteristics $\,T_{C}=25^{\circ}C\pm3^{\circ}C$

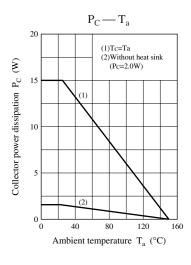
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 30 \text{ mA}, I_B = 0$	80			V
Base-emitter voltage	V <sub>BE</sub>	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$			1.8	V
Collector-emitter cutoff current (E-B short)	I <sub>CES</sub>	$V_{CB} = 80 \text{ V}, V_{BE} = 0$			100	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 60 \text{ V}, I_{B} = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 6 \text{ V}, I_C = 0$			100	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}$	70		320	_
	h <sub>FE2</sub>	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	10			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 3 \text{ A}, I_B = 0.375 \text{ A}$			1.2	V
Transition frequency	$f_T$	$V_{CE} = 5 \text{ V}, I_{C} = 0.2 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = 1 \text{ A}, I_{B1} = 0.1 \text{ A}, I_{B2} = -0.1 \text{ A}$		0.3		μs
Storage time	t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$		2.5		μs
Fall time	$t_{\rm f}$			0.2		μs

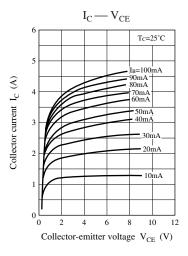
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

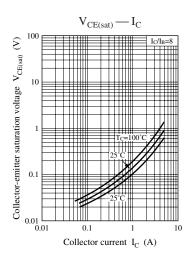
#### 2. \*: Rank classification

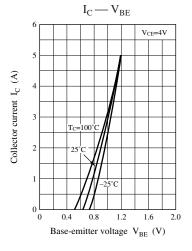
Rank	Q	Р	0
h <sub>FE1</sub>	70 to 150	120 to 250	160 to 320

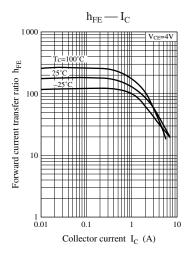
## **Panasonic**

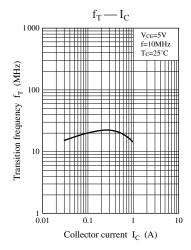


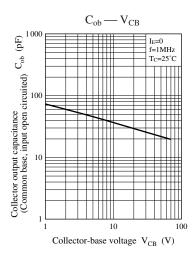


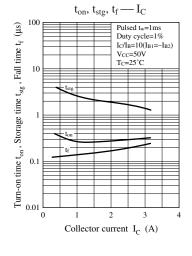


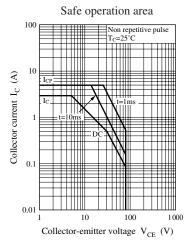




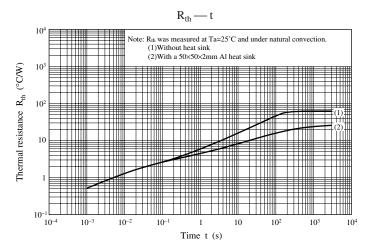








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